

Insulation and renovation board

UZIN Multimoll Top 7



Stress-relieving underlay with impact sound and heat insulating properties for subsequent installation of wood flooring and floor covering

Areas of application:

Stress-relief board, 7 mm thick, as stress-relieving layer under wood flooring and floor covering. For stress-relief or height compensation of new substrates or unfavourable / problematic subfloors such as somewhat deformed or cracked substrates. For interior use.

Main area of application:

- ▶ Stress-relief
- ▶ Fabricating a substrate ready for covering

Extended area of application:

- ▶ Height compensation of existing substrates
- ▶ Impact sound and heat insulation
- ▶ on cementitious screeds, calcium sulphate screeds or concrete
- ▶ on old substrates with strongly bonded compound and adhesive layers
- ▶ on new, firmly screw-fixed chipboard P4 – P7 or OSB 2 – OSB 4 panels
- ▶ on mastic asphalt
- ▶ on precast screeds, gypsum fibre boards
- ▶ on warm water underfloor heating (please consult UZIN Technical)
- ▶ for high wear in residential, commercial and industrial areas, e.g. in hospitals, shopping malls, etc.

Product benefits / features:

UZIN Multimoll Top 7 is a multi-ply board for renovation work. The insulation and renovation board protects the substrate and top floor against overload from shearing and tensile forces even under high loads and wear. In addition, UZIN Multimoll Top 7 increases walking comfort and indoor ambience of poorly heat-insulated substrates. Height differences to adjacent rooms or floor coverings can also be compensated for quickly and easily.

UZIN Multimoll Top 7 provide maximum safety against emission and take contribute to a healthy room atmosphere. Characterised with the **Blue Angel** eco label for low emission underlays for floor coverings according to RAL-UZ 156.



UZIN ÖKOLINE



Composition: Compressed synthetic fibre blend covered with fleece on both sides.

- ▶ Universal use
- ▶ Stress-relieving
- ▶ Suitable for height compensation
- ▶ Easy to process
- ▶ Impact sound and heat insulating properties
- ▶ Improves living and walking comfort
- ▶ EMICODE EC 1 PLUS / very low-emission
- ▶ RAL-UZ 156 / Environmentally compatible because of low emission

Technical data:

Packaging:	Carton
Packsize:	Carton with 9 boards = 5.4 m ² Pallet with 120 boards = 72 m ²
Board size:	0.6 m x 1.0 m = 0.6 m ²
Board thickness:	approx. 7 mm
Shelf life:	min. 24 months
Colour:	Tinged with white
Area weight:	approx. 4.5 kg/m ²
Traffic load capacity:	approx. 5 kN/m ²
Acoustic insulation improvement*:	approx. 12 dB
Thermal resistance (R)**:	0.088 m ² K/W
Thermal conductance (U-value)**:	11.36 W/m ² K
Building materials class***:	B 2

* Acoustic insulation improvement tested with 2-ply wood flooring, 10 mm, bonded with UZIN MK 250. see "Important notes".

** According to DIN EN 12 667

*** According to DIN 4102

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Substrate preparation:

The substrate must be sound, plane, dry, free from cracks, clean and free from materials (dirt, oil, grease), that would impair adhesion. Test the substrate in accordance with applicable standards and bulletins and report any deficiencies. Cement and calcium sulphate screeds must be abraded and vacuumed off. Remove unstable layers that would reduce adhesion, e.g. by brushing off, abrading, grinding or shot-blasting. Thoroughly vacuum loose material and dust. Use a suitable primer from the UZIN Product Guide according to the type and condition of the substrate.

The product data sheets of the other products used must be observed.

Processing:

1. Apply adhesive uniformly with suitable notched trowel (see "adhesive/consumption data") onto the substrate. Do not apply more adhesive to the substrate than can be laid with good wetting of the back of the board within the working time.
2. Install boards in combination and avoid cross joints. Cut boards to size with utility blade, jig saw (fine wood blade) or circular saw. For mineral substrates observe a distance of approx. 5 mm, for wooden substrates approx. 15 mm to all vertical structures.
3. Place boards right away in the fresh adhesive bed and roll-out with a heavy segmented roller or press down over whole area using a rubbing strip.
4. Installed board areas are ready for covering – depending on the adhesive – after 12 – 24 hours.

Wood flooring installation:

1. Install wood flooring using the same adhesive as with the UZIN Multimoll Top 7 installation.

Installation of floor covering:

1. Prime with UZIN PE 630.
2. Smooth surface with suitable UZIN self-levelling compound and allow to dry well.
3. Install floor covering with suitable UZIN adhesive.

Adhesive / consumption data:

Adhesive	Notch size	Consumption
UZIN MK 250	B 11	1000 – 1200 g/m ²
UZIN MK 92 S	B 11	1000 – 1200 g/m ²

Important notes:

- ▶ Shelf life of original pack at least 24 months when stored horizontally under moderately cool and dry conditions. Frost-resistant to – 25 °C.
- ▶ Optimum working at 18 – 25 °C, floor temperature above 15 °C and relative humidity below 65%.
- ▶ The respective coefficient of improvement of sound absorption specified represents a guide value ascertained under standard conditions. The values may differ due to the individual acoustics of each building and the materials used, as well as possible flooring construction. To determine the actually achieved coefficient of improvement of sound absorption, the measurement and its assessment must be performed under real conditions.
- ▶ On underfloor heating floor covering should not exceed HTR of 0.15 m² K/W according to DIN EN 1264. The HTR of the double-layer underlay / floor covering is derived as some of their individual HTR values.
- ▶ Expansion, movement and perimeter joints in the substrate must be adopted. Fit UZIN Foam Expansion Strips to any adjoining rising structures to prevent ingress of the compound into the connection joints. Expansion strips are generally necessary for thicknesses over 5 mm. On wooden substrates the expansion strip must be completely removed after levelling work.
- ▶ The substructure of wooden floors must be dry. Adequate ventilation or rear-ventilation must be provided, e.g. by removing the existing expansion strip or by installing special skirting with vent openings.
- ▶ Mastic asphalt screeds must be well sanded and exhibit a continuous and sufficiently wide perimeter joint. Obtain application consulting for old mastic asphalt screeds.
- ▶ Ensure solid drying of the companion products, such as primers, levelling compounds, etc.
- ▶ Observe the generally acknowledged rules of the trade and technology for the installation of floor covering or wood flooring as well as the respective applicable national standards (e.g. EN, DIN, VOB, Austrian Ö-Norm, SIA, etc.). The following standards and bulletins represent supporting information and are recommended for special attention:
 - DIN 18 365 "Working with floor covering", Ö-Norm B 2236
 - DIN 18 356 "Working with wood flooring", Ö-Norm B 2218
 - DIN 18 352 "Tile and slab work"
 - TKB publication "Assessment and preparation of substrates for floor covering and wood flooring installation"
 - BEB publication "Assessment and preparation of substrates"
 - TKB publication "Technical description and processing of cementitious floor levelling compounds"
 - Technical bulletin of the Central Association of the German Building Construction Trade (ZDB) "Resilient floor covering, textile floor covering and wood flooring on heated under-floor constructions"

Protection of the workplace and the environment:

No special measures are required. Refer to the notes on protection of the workplace and the environment in the Product Information Sheets for the other installation materials used.

EMICODE EC 1 PLUS – "Very low emission" – Within the scope of current knowledge, gives off no emissions of formaldehyde, hazardous materials or volatile organic compounds (VOC).

Disposal:

All product residues are treated as normal construction waste.

